Low Skew, 1-to-16 LVCMOS/LVTTL Clock Generator

DATASHEET

Description

RENESAS

The 87016I is a low skew, 1:16 LVCMOS/LVTTL Clock Generator. The device has four banks of four outputs and each bank can be independently selected for \div 1 or \div 2 frequency operation. Each bank also has its own power supply pins so that the banks can operate at the following different voltage levels: 3.3V, 2.5V, and 1.8V. The low impedance LVCMOS/LVTTL outputs are designed to drive 50 Ω series or parallel terminated transmission lines.

The divide select inputs, DIV_SELA:DIV_SELD, control the output frequency of each bank. The output banks can be independently selected for ÷1 or ÷2 operation. The bank enable inputs, CLK_ENA:CLK_END, support enabling and disabling each bank of outputs individually. The CLK_ENA:CLK_END circuitry has a synchronizer to prevent runt pulses when enabling or disabling the clock outputs. The master reset input, MR/OE, resets the ÷1/÷2 flip flops and also controls the active and high impedance states of all outputs. This pin has an internal pull-up resistor and is normally used only for test purposes or in systems which use low power modes.

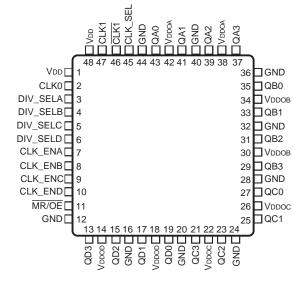
The 87016I is characterized to operate with the core at 3.3V or 2.5V and the banks at 3.3V, 2.5V, or 1.8V. Guaranteed bank, output, and part-to-part skew characteristics make the 87016I ideal for those clock applications demanding well-defined performance and repeatability.

Features

- Sixteen LVCMOS/LVTTL outputs (4 banks of 4 outputs)
- Selectable differential CLK1/CLK1 or LVCMOS/LVTTL clock input
- CLK1, CLK1 pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- CLK0 supports the following input types: LVCMOS, LVTTL
- Maximum output frequency: 250MHz
- Independent bank control for ÷1 or ÷2 operation
- Independent output bank voltage settings for 3.3V, 2.5V, or 1.8V operation
- Asynchronous clock enable/disable
- Output skew: 170ps (maximum)
- Bank skew: 50ps (maximum
- Part-to-Part Skew: 800ps (maximum)
- Supply modes: Core/Output
 3.3V/3.3V
 3.3V/2.5V
 3.3V/1.8V
 2.5V/2.5V
 2.5V/1.8V
- -40°C to 85°C ambient operating temperature
- · Lead-free packaging

Pin Assignment

1



48-LQFP 7 × 7 × 1.4 mm package body Y Package Top View

87016I

Block Diagram

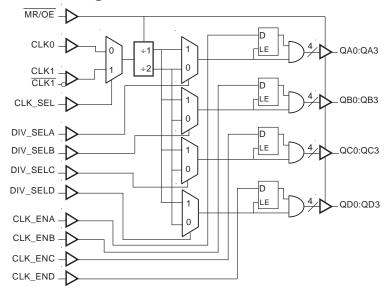


Table 1. Pin Descriptions

Number	Name	Ту	/ре	Description
1, 48	V _{DD}	Power		Positive supply pins.
2	CLK0	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
3	DIV_SELA	Input	Pullup	Controls frequency division for Bank A outputs. See Table 3. LVCMOS / LVTTL interface levels.
4	DIV_SELB	Input	Pullup	Controls frequency division for Bank B outputs. See Table 3. LVCMOS / LVTTL interface levels.
5	DIV_SELC	Input	Pullup	Controls frequency division for Bank C outputs. See Table 3. LVCMOS / LVTTL interface levels.
6	DIV_SELD	Input	Pullup	Controls frequency division for Bank D outputs. See Table 3. LVCMOS / LVTTL interface levels.
7	CLK_ENA	Input	Pullup	Output enable for Bank A outputs. Active HIGH. If pin is LOW, outputs drive low. LVCMOS/LVTTL interface levels. See Table 3.
8	CLK_ENB	Input	Pullup	Output enable for Bank A outputs. Active HIGH. If pin is LOW, outputs drive low. LVCMOS/LVTTL interface levels. See Table 3.
9	CLK_ENC	Input	Pullup	Output enable for Bank A outputs. Active HIGH. If pin is LOW, outputs drive low. LVCMOS/LVTTL interface levels. See Table 3.
10	CLK_END	Input	Pullup	Output enable for Bank A outputs. Active HIGH. If pin is LOW, outputs drive low. LVCMOS/LVTTL interface levels. See Table 3.
11	MR/OE	Input	Pullup	Master reset. When LOW, resets the ÷1/÷2 flip flops and sets the outputs to high impedance. LVCMOS / LVTTL interface levels.
12, 16, 20, 24, 28, 32, 36, 40, 44	GND	Power		Power supply ground
13, 15, 17, 19	QD3, QD2, QD1, QD0	Output		Bank D single-ended clock outputs. LVCMOS/LVTTL interface levels.
14, 18	V _{DDOD}	Power		Bank D output supply pins.
21, 23, 25, 27	QC3, QC2, QC1, QC0	Output		Bank C single-ended clock outputs. LVCMOS/LVTTL interface levels.
22, 26	V _{DDOC}	Power		Bank C output supply pins.
29, 31, 33, 35	QB3, QB2, QB1, QB0	Output		Bank C single-ended clock outputs. LVCMOS/LVTTL interface levels.
30, 34	V _{DDOB}	Power		Bank B output supply pins.
37, 39, 41, 43	QA3, QA2, QA1, QA0	Output		Bank A single-ended clock outputs. LVCMOS/LVTTL interface levels.
38, 42	V _{DDOA}	Power		Bank B output supply pins.
45	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1, CLK1 inputs. When LOW, selects CLK0 input. LVCMOS / LVTTL interface levels.
46	CLK1	Input	Pullup	Inverting differential clock input.
47	CLK1	Input	Pulldown	Non-inverting differential clock input.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pull-up Resistor			51		kΩ
R _{PULLDOWN}	Input Pull-down Resistor			51		kΩ
		V _{DD,} V _{DDOx} = 3.465V			18	pF
		V _{DD,} V _{DDOx} = 2.625V			12	pF
C _{PD}	Power Dissipation Capacitance	V _{DD} = 3.465V, V _{DDOx} = 2.625V			20	pF
	(per output); NOTE 1	V _{DD} = 3.465V, V _{DDOx} = 1.89V			30	pF
		V _{DD} = 2.625V, V _{DDOx} = 1.89V			14	pF
R _{OUT}	Output Impedance		5	7	12	Ω

NOTE 1: V_{DDOx} denotes V_{DDOA}, V_{DDOB}, V_{DDOC}, V_{DDOD}.

Function Tables

Table 3. Function Table

	Inputs		Out	puts
MR/OE	CLK_ENx	DIV_SELx	Bank [A:D]	Qx Frequency
0	Х	Х	Hi-Z	N/A
1	1	0	Active	fIN/2
1	1	1	Active	fIN
1	0	Х	LOW	N/A

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V _{CC}	4.6V
Inputs, V _I	-0.5V to V _{DD} + 0.5V
Outputs, V _O	-0.5V to V _{DD Ox} + 0.5V
Package Thermal Impedance, θ_{JA}	47.9°C/W (0 lfpm)
Storage Temperature, T _{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDOx} = 3.3V ± 5%, 2.5V ± 5%, 1.8V ± 5%, T_A = -40°C to 85°C t

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
V _{DDOA,}			3.135	3.3	3.465	V
V _{DDOB,} V _{DDOC,}	Output Supply Voltage		2.375	2.5	2.625	V
V _{DDOD}			1.71	1.8	1.89	V
I _{DD}	Power Supply Current				100	mA
I _{DDOA,} I _{DDOB,} I _{DDOC,} I _{DDOD}	Output Supply Current				15	mA

Table 4B. Power Supply DC Characteristics, V_{DD} = 2.5V ± 5%, V_{DDOx} = 2.5V ± 5%, 1.8V ± 5%, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{DD}	Positive Supply Voltage		2.375	2.5	2.625	V
V _{DDOA,}	_		2.375	2.5	2.625	V
V _{DDOB,} V _{DDOC,} V _{DDOD}	Output Supply Voltage		1.71	1.8	1.89	V
I _{DD}	Power Supply Current				95	mA
I _{DDOA,} I _{DDOB,} I _{DDOC,} I _{DDOD}	Output Supply Current				8	mA

Symbol	Paramete	r	Test Conditions	Minimum	Typical	Maximum	Units
M	Input High Voltage	Valtara	V _{DD} = 3.465V	2		V _{DD} + 0.3	V
V _{IH}	Input High	vollage	V _{DD} = 2.625V	1.7		V _{DD} + 0.3	V
N/	Input Low Voltage Input High Current CLK0, CLK_SEL CLK_EN[A:D], DIV_SEL[A:D], MR/OE Input Low Current CLK0, CLK_SEL CLK_EN[A:D], DIV_SEL[A:D], MR/OE Output High Voltage;	V _{DD} = 3.465V	-0.3		0.8	V	
V _{IL}			V _{DD} = 2.625V	-0.3		0.7	V
	Input Low Voltage Input High Current Input Low Current CLK0, CLK_S CLK_EN[A:D] DIV_SEL[A:D] MR/OE CLK0, CLK_S CLK_EN[A:D] DIV_SEL[A:D] MR/OE Output High Voltage; NOTE 1	CLK0, CLK_SEL	V _{DD} = V _{IN} = 3.465V or 2.625V			150	μA
I _{IH}	High	DIV_SEL[A:D],	V _{DD} = V _{IN} = 3.465V or 2.625V			5	μA
	lawit	CLK0, CLK_SEL	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-5			μA
I _{IL}	Low	DIV_SEL[A:D],	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-150			μΑ
			V _{DDOx} = 3.3V ± 5%	2.6			V
V _{OH}		gh Voltage;	V _{DDOx} = 2.5V ± 5%	1.8			V
- OH	NOTE 1		V _{DDOx} = 1.8V ± 5%; I _{OH} = -2mA	V _{DDOx} - 0.45			V
			V _{DDOx} = 3.3V ± 5%			0.5	V
V _{OL}		w Voltage;	V _{DDOx} = 2.5V ± 5%			0.5	V
UL	NOTE 1		V _{DDOx} = 1.8V ± 5%; I _{OH} = 2mA			0.45	V
I _{OZL}	Output Hi-	Z Current Low		-5			μA
I _{OZH}	Output Hi-	Z Current High				5	μA

Table 4C. LVCMOS/LVTTL DC Characteristics, $T_A = -40^{\circ}C$ to $85^{\circ}C$

NOTE 1: Outputs terminated with 50Ω to V_{DDOX}/2. See Parameter Measurement Information, Output Load Test Circuit diagrams.

Table 4D. Differential DC Characteristics, T_A = -40°C to $85^\circ C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
1	Input High Current	CLK1	V _{DD} = V _{IN} = 3.465V or 2.625V			5	μA
ΙΗ	input nigh Current	CLK1	V _{DD} = V _{IN} = 3.465V or 2.625V			150	μA
1	Input Low Current	CLK1	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-150			μA
ΊL		CLK1	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-5			μA
V _{PP}	Peak-to-Peak Voltage	Э		0.15		1.3	V
V _{CMR}	Common Mode Input Voltage; NOTE 1, 2			GND + 0.5		V _{DD} – 0.85	V

NOTE 1: Common mode input voltage is defined as V_{IH}. NOTE 2: For single-ended applications, the maximum input voltage for CLK1, $\overline{\text{CLK1}}$ is V_{DD} + 0.3V.

AC Electrical Characteristics

Table 5A. AC Characteristics,	, V _{DD} = V _{DDC}	_{0x} = 3.3V ± 5%, T _A	$= -40^{\circ}$ C to 85°C
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Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
MAX	Output Freque	ency				250	MHz
	Propagation	CLK0; NOTE 1A		2.8	3.4	3.9	ns
tp _{LH}	Delay, Low to High	CLK1/CLK1; NOTE 1B		2.75	3.4	4.1	ns
<i>t</i> sk(b)	Bank Skew; NOTE 2, 6		Measured on the Rising Edge			50	ps
<i>t</i> sk(o)	Output Skew;	NOTE 3, 6	Measured on the Rising Edge			170	ps
<i>t</i> sk(pp)	Part-to-Part S	kew; NOTE 4, 6				800	ps
t _R / t _F	Output Rise/F NOTE 5	all Time;	20% to 80%	200		700	ps
odo			<i>f</i> < 175MHz	45		55	%
odc	Output Duty Cycle		$f \ge 175 MHz$	40		60	%
t _{EN}	Output Enable	e Time; NOTE 5				10	ns
t _{DIS}	Output Disabl	e Time; NOTE 5				10	ns

All parameters measured at 250MHz unless noted otherwise.

NOTE 1A: Measured from the $V_{\text{DD}}/2$ of the input to $V_{\text{DDOX}}/2$ of the output.

NOTE 1B: Measured from the differential input crossing point to V_{DDOX}/2 of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDOX}/2.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at V_{DDOX}/2.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

Table 5B. AC Characteristics, $V_{DD} = V_{DDOx} = 2.5V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Freque	ency				250	MHz
to	Propagation	CLK0; NOTE 1A		2.9	3.8	4.7	ns
tp _{LH}	Delay, Low to High	CLK1/CLK1; NOTE 1B		3.0	3.6	4.3 70 210 800 700	ns
<i>t</i> sk(b)	Bank Skew; NOTE 2, 6		Measured on the Rising Edge			70	ps
<i>t</i> sk(o)	Output Skew; NOTE 3, 6		Measured on the Rising Edge			210	ps
<i>t</i> sk(pp)	Part-to-Part Skew; NOTE 4, 6					800	ps
t _R / t _F	Output Rise/Fall Time; NOTE 5		20% to 80%	150		700	ps
odc	Output Duty C	Cycle	$f \leq 125 MHz$	40		60	%
t _{pw}	Output Pulse	Width	<i>f</i> > 125MHz	t _{Period} /2-800		t _{Period} /2 + 800	ps
t _{EN}	Output Enable	e Time; NOTE 5				10	ns
t _{DIS}	Output Disable	e Time; NOTE 5				10	ns

For NOTES, please see above, Table 5A.

Parameter	Symbol		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					250	MHz
to	Propagation	CLK0; NOTE 1A		2.9	3.5	4.0	ns
tp _{LH}	Delay, Low to High	CLK1/CLK1; NOTE 1B		3.0 3.5	50 r	ns	
<i>t</i> sk(b)	Bank Skew; N	OTE 2, 6	Measured on the Rising Edge			50	ps
<i>t</i> sk(o)	Output Skew; I	NOTE 3, 6	Measured on the Rising Edge			170	ps
<i>t</i> sk(pp)	Part-to-Part Sk	ew; NOTE 4, 6				800	ps
t _R / t _F	Output Rise/Fa	all Time; NOTE 5	20% to 80%	200		700	ps
odo			<i>f</i> < 175MHz	45		55	%
odc	Output Duty Cycle		<i>f</i> ≥ 175MHz	40		60	%
t _{EN}	Output Enable	Time; NOTE 5				10	ns
t _{DIS}	Output Disable	e Time; NOTE 5				10	ns

Table 5C. AC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDOx} = 2.5V ± 5%, T_A = -40°C to 85°C

All parameters measured at 250MHz unless noted otherwise.

NOTE 1A: Measured from the $V_{DD}/2$ of the input to $V_{DDOX}/2$ of the output.

NOTE 1B: Measured from the differential input crossing point to $V_{DDOX}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDOX}/2.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at $V_{DDOX}/2$.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

Table 5D. AC Characteristics, V_{DD} = 3.3V ± 5%, V_{DDOx} = 1.8V ± 5%, T_A = -40°C to 85°C

Parameter	Symbol Output Frequency		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}						250	MHz
tp _{LH}	Propagation Delay, Low to High	CLK0; NOTE 1A		3.0	3.9	4.7	ns
		CLK1/CLK1; NOTE 1B		3.0	3.9	4.7	ns
<i>t</i> sk(b)	Bank Skew; NOTE 2, 6		Measured on the Rising Edge			50	ps
<i>t</i> sk(o)	Output Skew; NOTE 3, 6		Measured on the Rising Edge			170	ps
<i>t</i> sk(pp)	Part-to-Part Skew; NOTE 4, 6					800	ps
t _R / t _F	Output Rise/Fall Time; NOTE 5		20% to 80%	200		700	ps
odc	Output Duty Cycle		<i>f</i> < 175MHz	45		55	%
			<i>f</i> ≥ 175MHz	40		60	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time; NOTE 5					10	ns

For NOTES, please see above, Table 5C.

Parameter	Symbol Output Frequency		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}						250	MHz
tp _{LH}	Propagation Delay, Low to High	CLK0; NOTE 1A		3.1	4.1	5.2	ns
		CLK1/CLK1; NOTE 1B		3.0	3.9	4.7	ns
<i>t</i> sk(b)	Bank Skew; NOTE 2, 6		Measured on the Rising Edge			70	ps
<i>t</i> sk(o)	Output Skew; NOTE 3, 6		Measured on the Rising Edge			210	ps
<i>t</i> sk(pp)	Part-to-Part Skew; NOTE 4, 6					800	ps
t _R / t _F	Output Rise/Fall Time; NOTE 5		20% to 80%	150		700	ps
odc	Output Duty Cycle		<i>f</i> < 175MHz	45		55	%
			<i>f</i> ≥ 175MHz	40		60	%
t _{EN}	Output Enable Time; NOTE 5					10	ns
t _{DIS}	Output Disable Time; NOTE 5					10	ns

Table 5E. AC Characteristics, V_{DD} = 2.5V ± 5%, V_{DDOx} = 1.8V ± 5%, T_A = -40°C to 85°C

All parameters measured at 250MHz unless noted otherwise.

NOTE 1A: Measured from the $V_{DD}/2$ of the input to $V_{DDOX}/2$ of the output.

NOTE 1B: Measured from the differential input crossing point to $V_{DDOX}/2$ of the output.

NOTE 2: Defined as skew within a bank with equal load conditions.

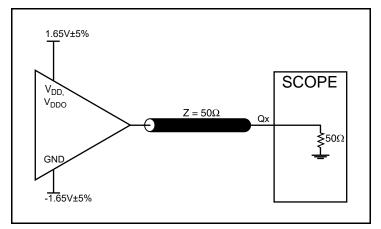
NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDOX}/2.

NOTE 4: Defined as skew between outputs on different devices operating a the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at V_{DDOX}/2.

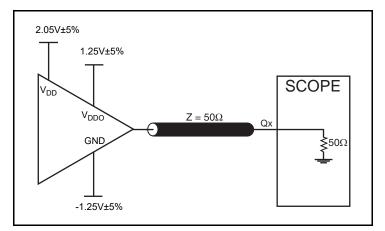
NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

NOTE 6: This parameter is defined in accordance with JEDEC Standard 65.

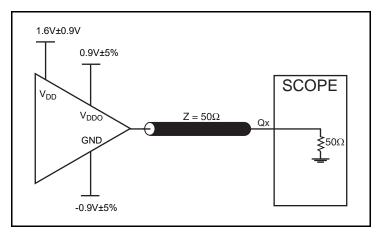
Parameter Measurement Information



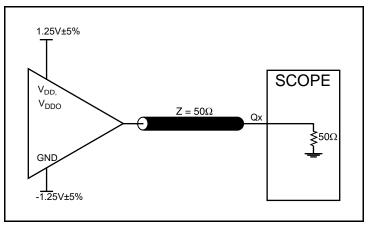
3.3V Core/3.3V LVCMOS Output Load Test Circuit



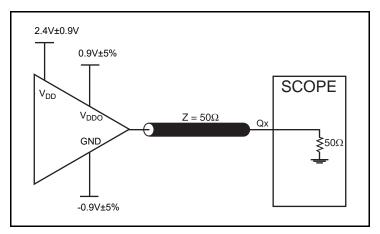
3.3V Core/2.5V LVCMOS Output Load Test Circuit



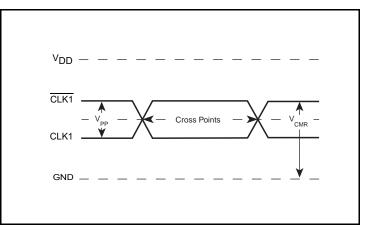
2.5V Core/1.8V LVCMOS Output Load Test Circuit



2.5V Core/2.5V LVCMOS Output Load Test Circuit

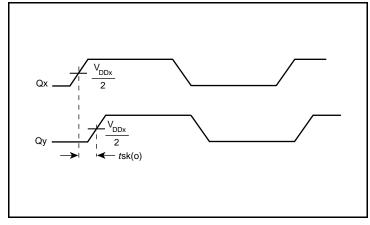


3.3V Core/1.8V LVCMOS Output Load Test Circuit

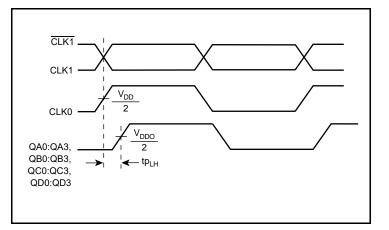


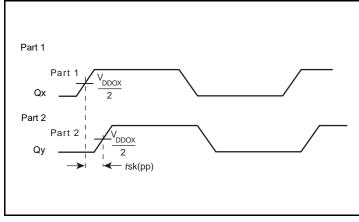
Differential Input Level

Parameter Measurement Information, continued

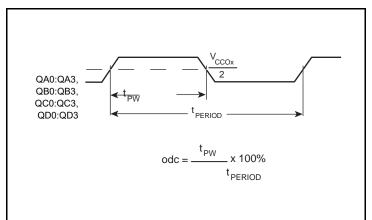


Output Skew



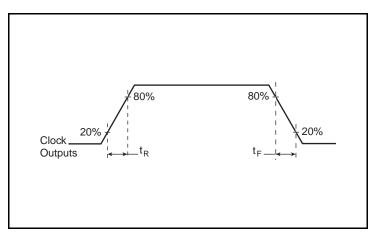


Part-to-Part Skew



Output Duty Cycle/Pulse Width/Period

Propagation Delay



Output Rise/Fall Time

Application Information

Wiring the Differential Input to Accept Single Ended Levels

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage V_REF = $V_{DD}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V_{DD} = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.

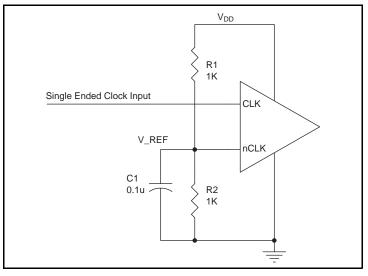


Figure 1. Single-Ended Signal Driving Differential Input

Recommendations for Unused Input and Output Pins

Inputs

CLK/CLK Inputs

For applications not requiring the use of the differential input, both CLK and $\overline{\text{CLK}}$ can be left floating. Though not required, but for additional protection, a 1k Ω resistor can be tied from CLK to ground.

CLK Input

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a $1k\Omega$ resistor can be tied from the CLK input to ground.

LVCMOS Control Pins

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A $1k\Omega$ resistor can be used.

Outputs

LVCMOS Outputs

All unused LVCMOS output can be left floating. There should be no trace attached.

Differential Clock Input Interface

The CLK /CLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the V_{PP} and V_{CMR} input requirements. *Figures 2A to 2E* show interface examples for the CLK/CLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the

vendor of the driver component to confirm the driver termination requirements. For example, in Figure 2A, the input termination applies for Renesas LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

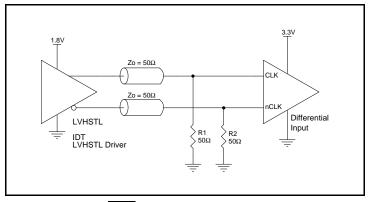
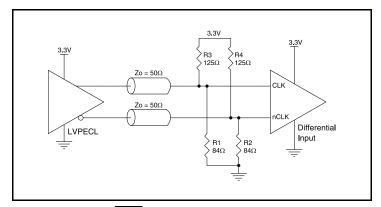


Figure 2A. CLK/CLK Input Driven by a Renesas LVHSTL Driver





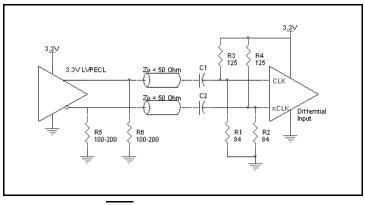
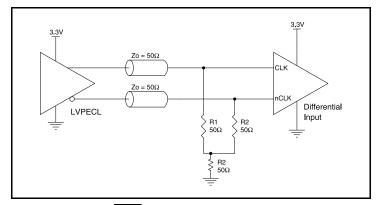


Figure 2E. CLK/CLK Input Driven by a 3.3V LVPECL Driver with AC Couple





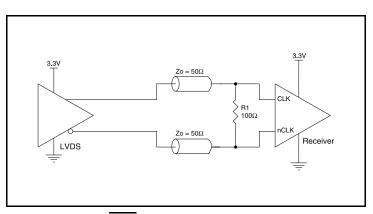


Figure 2D. CLK/CLK Input Driven by a 3.3V LVDS Driver

Reliability Information

Table 6. θ_{JA} vs. Air Flow Table for a 48-LQFP

θ_{JA} vs. Air Flow				
Linear Feet per Minute	0	200	500	
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W	
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W	

NOTE: Most modern PCB design use multi-layered boards. The data in the second row pertains to most designs.

Transistor Count

The transistor count for 87016I is: 2034

Package Outline Drawings

The package outline drawings are appended at the end of this document and are accessible from the link below. The package information is the most current data available.

www.idt.com/us/en/document/cpt/prprg-package-outline-70-x-70-x-14-mm-tqfp-10010-form

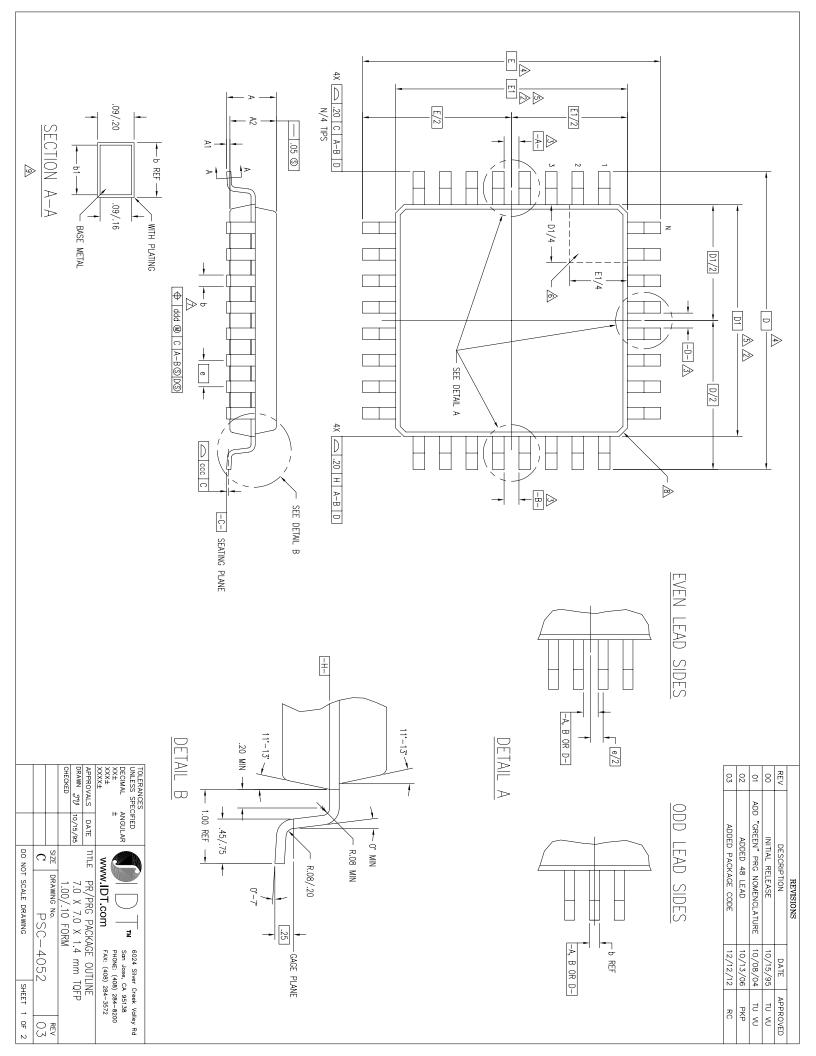
Ordering Information

Table 8. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS87016AYILF	ICS87016AYIL	"Lead-Free" 48 Lead LQFP	Tray	-40°C to 85°C
ICS87016AYILFT	ICS87016AYIL	"Lead-Free" 48 Lead LQFP	Tape & Reel	-40°C to 85°C

Revision History

Date	Description of Change
January 22, 2020	 Updated package outline drawings section; added link. Updated logos and footer information.
March 23, 2015	Ordering Information - updated part marking. Updated datasheet format.
March 28, 2013	Corrected typo, VOH: $V_{DD} - 0.45$ to $V_{DDOx} - 0.45$
November 15, 2012	Remove leaded parts from Ordering Information table.
May 25, 2007	2.5V AC Characteristics Table - changed Output Duty Cycle test condition and limits. Added Output Pulse Width.
March 30, 2007	Features Section - added 2.5V/2.5V and 2.5V/1.8V to supply mode bullet. Added lead-free bullet. Pin Characteristics Table - added 2.5V/2.5V and 2.5V/1.8V to C _{PD} . Added 2.5V Power Supply DC Characteristics Table. LVCMOS DC Characteristics Table - added 2.5V to V _{IH} /V _{IL} . Differential DC Characteristics Table - added 2.5V to I _{IH} /I _{IL} . Added 2.5V Power Supply DC Characteristics Table. Added 2.5V Power Supply DC Characteristics Table. Added 2.5V/1.8V Power Supply DC Characteristics Table. Parameter Measurement Information - added 2.5V Core/2.5V Output Load Test Circuit and 2.5V Core/1.8V Output Load Test Circuit diagrams. Added <i>Recommendations for Unused Input and Output Pins</i> . Ordering Information Table - added lead-free Order/Part Number.



EXACT SHAPE OF EACH CORNER IS OPTIONAL THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP ALL DIMENSIONS ARE IN MILLIMETERS THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-026, VARIATIONS BBA & BBC.	DATUMS <u>A-B</u> AND <u>-D-</u> TO BE DETERMINED AT DATUM PLANE <u>-H-</u> DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE <u>-C-</u> DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH DETAILS OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE 6 DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.	1.35 1.40 1.45 A2 1.35 1.40 1 9.00 BSC 4 D 9.00 BSC 1 9.00 BSC 5,2 D1 7.00 BSC 1 3.0 .30 .37 .45 7 6 .17 .20 8 .30 .37 .45 7 6 .17 .22 .2 .20	PR/PRG32 PR/PRG32 PR/PRG32 PR/PRG48 PR/PRG
TOLERANCES UNLESS SPECIFIED DECIMAL XXX± Image: Construction of the sector of the	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		REVISIONS REVISIONS NITIAL RELEASE 01 ADD "GREEN" PRG NOMENCLATURE 10/15/95 TU VU 02 ADDED 48 LEAD 10/13/06 PKP 03 ADDED PACKAGE CODE 12/12/12 RC N N N N N N N N N N N N N

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(Rev.1.0 Mar 2020)

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